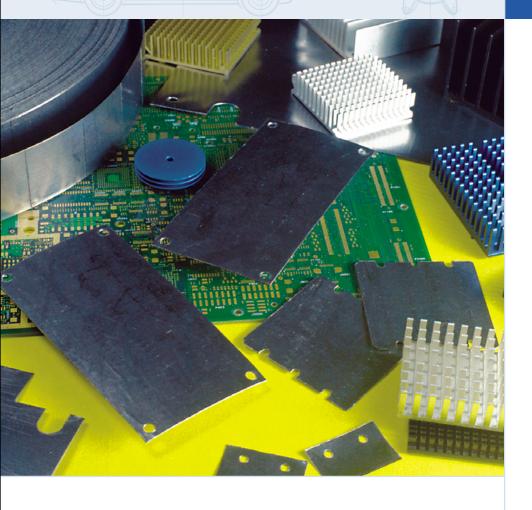
# HERMAGON, INC. A DIVISION OF LAIRD TECHNOLOGIES



#### **Electrically Conductive Interface Pads**

- High thermal conductivity of 5 W/mK in Z axis and 140 W/mK in the X-Y axis
- >98% Graphite
- Low thermal resistance
- Thicknesses of 0.005", 0.010" & 0.020" (0.125mm, 0.25mm, & 0.50mm)

#### **Applications Include:**

- Power Conversion Equipment
- Power Supplies
- Large Telecommunications Switching Hardware
- Notebook Computers

## T-gon<sup>™</sup> 800 Series (Replaces CM20)

T-gon<sup>™</sup> 800 is a high performance, costeffective thermal interface material. T-gon<sup>™</sup>
800 is used where electrical isolation is not
required. Its unique grain-oriented, plate
like structure allows it to conform exactly
to surfaces, thus maximizing heat transfer.

T-gon<sup>™</sup> 800 can be supplied in 12" x 18"

(305mm x 457mm) or 18" x 24" (457mm x 610mm) sheets, in rolls, or die cut to specific configurations. T-gon<sup>™</sup> 800 is available with proprietary pressure sensitive adhesive on one side. This adhesive coating is the thinnest available, thereby minimizing any impact on thermal performance.

Gap Fillers | Thermally Conductive Insulators | Thermally Conductive PCB Materials | Greases | Phase Change Materials









### T-gon<sup>™</sup> 800 Series (Replaces CM20)

	T-gon™ 805	T-gon™ 810	T-gon™ 820	Test Method
Construction & Composition	Flexible graphite	Flexible graphite	Flexible graphite	
Color	Pewter	Pewter	Pewter	Visual
Thickness	0.005" (0.13mm)	0.010" (0.25mm)	0.020" (0.51mm)	
Thickness Tolerance	± 0.001" (± 0.025mm)	± 0.001" (± 0.025mm)	± 0.002" (± 0.05mm)	
Density	2.20 g/cc	2.20 g/cc	2.20 g/cc	Helium Pycnometer
Hardness	85 Shore A	85 Shore A	85 Shore A	ASTM D2240
Tensile Strength	650 psi	650 psi	650 psi	ASTM D412
% Elongation	N/A	N/A	N/A	ASTM D412
Outgassing TML	0.15%	0.15%	0.15%	ASTM E595
Outgassing CVCM	0.09%	0.09%	0.09%	ASTM E595
UL Flammability Rating	94 VO	94 VO	94 VO	E180840
Temperature Range	-240°C to 300°C	-240°C to 300°C	-240°C to 300°C	ASTM D5470 (modified)
Thermal Conductivity	5 W/mK	5 W/mK	5 W/mK	
Thermal Impedance @ 100 psi @ 681 KPa	0.07 °C-in²/W 0.42 °C-cm²/W	0.10 °C-in²/W 0.66 °C-cm²/W	0.17 °C-in²/W 1.07 °C-cm²/W	ASTM D5470 (modified)
Volume Resistivity	11 x 10 <sup>-4</sup> ohm-cm	11 x 10 <sup>-4</sup> ohm-cm	11x 10⁴ ohm-cm	ASTM D257

**Standard Thicknesses:** 0.005" (0.13mm) 0.010" (0.25mm) 0.020" (0.51mm)

Consult the factory for alternate thicknesses

Standard Sheet Sizes: 18" x 24" (457mm x 609.6mm)

T-gon<sup>™</sup> 800 sheets are supplied with no liners when ordered without adhesive. With adhesive they are supplied with no top liner and white release liner on the bottom. T-gon<sup>™</sup> 800 is available on

rolls and individual die cut shapes.

**Pressure Sensitive** 

**Adhesive:** Request no adhesive with "AO" suffix

Request adhesive on one side with "A1" suffix

Double sided adhesive is not available

Our customers are reminded that they bear the responsibility for testing Thermagon, Inc. materials for their proposed use. Any information furnished by Thermagon, Inc. and its agents is believed to be accurate and reliable, but our customers must bear all responsibility for the use and application of Thermagon, Inc. materials since Thermagon and its agents cannot be aware of all potential uses. Thermagon makes no warranties as to the fitness, merchantability, or suitability of any Thermagon, Inc. materials or products for any specific or general uses. Thermagon, Inc. shall not be liable for incidental or consequential damages of any kind. All Thermagon, Inc. products are sold pursuant to the Thermagon, Inc. domestic terms and conditions of sale in effect from time to time, a copy of which will be furnished upon request.

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